

TLP383

1. Applications

- Programmable Logic Controllers (PLCs)
- · AC Adapters
- I/O Interface Boards

2. General

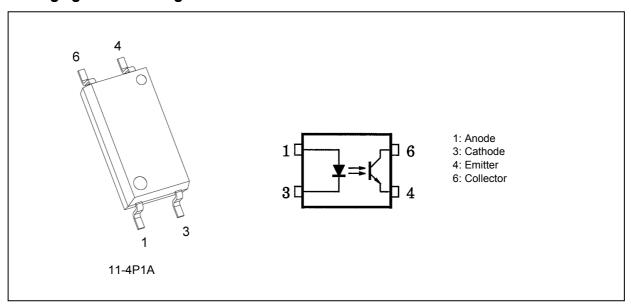
TLP383 is a photocoupler of low input and high isolation type that consists of phototransistor optically coupled to infrared LED in a 4-pin SO6L package. TLP383 is guaranteed high isolation voltage (5000 Vrms) and wide operating temperature (T_a = -55 to 125 °C). Since TLP383 has a small and thin package compared with a standard DIP package, it is suitable for high-density surface mounting applications such as programmable controllers.

3. Features

- (1) Collector-emitter voltage: 80 V (min)
- (2) Current transfer ratio: 50 % (min)
 - GB Rank: 100 % (min)
- (3) Isolation voltage: 5000 Vrms (min)
- (4) Operating temperature: -55 to 125 °C
- (5) Safety standards
 - UL-recognized: UL 1577, File No.E67349
 - cUL-recognized: CSA Component Acceptance Service No.5A File No.E67349
 - VDE-approved: EN 60747-5-5, EN 62368-1 **(Note 1)** CQC-approved: GB4943.1, GB8898 Thailand Factory

Note 1: When a VDE approved type is needed, please designate the Option (D4).

4. Packaging and Pin Assignment





5. Mechanical Parameters

Characteristics	Min	Unit
Creepage distances	8.0	mm
Clearance	8.0	
Internal isolation thickness	0.4	

6. Absolute Maximum Ratings (Note) (Unless otherwise specified, T_a = 25 °C)

	Characteristics		Symbol	Note	Rating	Unit
LED	Input forward current		I _F		50	mA
	Input forward current derating	$(T_a \ge 90 ^{\circ}C)$	$\Delta I_F/\Delta T_a$		-1.11	mA/°C
	Input forward current (pulsed)		I _{FP}	(Note 1)	1	Α
	Input power dissipation		P _D		100	mW
	Input power dissipation derating	(T _a ≥ 90 °C)	$\Delta P_D/\Delta T_a$		-2.22	mW/°C
	Input reverse voltage		V_R		5	\ \
	Junction temperature		Tj		135	ů
Detector	Collector-emitter voltage		V _{CEO}		80	\ \
	Emitter-collector voltage		V _{ECO}		7	\ \
	Collector current		I _C		50	mA
	Collector power dissipation		P _C		150	mW
	Collector power dissipation derating	$(T_a \ge 25 ^{\circ}C)$	$\Delta P_{C}/\Delta T_{a}$		-1.36	mW/°C
	Junction temperature		Tj		135	ů
Common	Operating temperature		T _{opr}		-55 to 125	ů
	Storage temperature		T _{stg}		-55 to 125	ů
	Lead soldering temperature	(10 s)	T _{sol}		260	°C
	Total power dissipation		P _T		250	mW
	Total power dissipation derating	(T _a ≥ 25 °C)	$\Delta P_T/\Delta T_a$		-2.27	mW/°C
	Isolation voltage	(AC, 60 s, R.H. ≤ 60 %)	BV _S	(Note 2)	5000	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Pulse width (PW) \leq 0.1 ms, f = 100 Hz

Note 2: This device is considered as a two-terminal device: Pins 1 and 3 are shorted together, and pins 4 and 6 are shorted together.



7. Electrical Characteristics (Unless otherwise specified, Ta = 25 °C)

	Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
LED	Input forward voltage	V _F		I _F = 10 mA	1.1	1.25	1.4	V
	Input reverse current	I _R		V _R = 5 V	_		5	μА
	Input capacitance	Ct		V = 0 V, f = 1 MHz	_	30	_	pF
Detector	Collector-emitter breakdown voltage	V _{(BR)CEO}		I _C = 0.5 mA	80			V
	Emitter-collector breakdown voltage	V _{(BR)ECO}		I _E = 0.1 mA	7			V
	Dark Current	I _{DARK}		V _{CE} = 48 V	_	0.01	0.08	μА
				V _{CE} = 48 V, T _a = 85 °C	_	2	50	
	Collector-emitter capacitance	C _{CE}		V = 0 V, f = 1 MHz	_	10	_	pF

8. Coupled Electrical Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Current transfer ratio	I _C /I _F	(Note 1)	I _F = 5 mA, V _{CE} = 5 V	50	_	600	%
			I _F = 5 mA, V _{CE} = 5 V, GB Rank	100	_	600	
			I _F = 0.5 mA, V _{CE} = 5 V	50		600	
			$I_F = 0.5 \text{ mA}, V_{CE} = 5 \text{ V}, GB \text{ Rank}$	100	_	600	
Saturated current transfer ratio	I _C /I _{F(sat)}		I _F = 1 mA, V _{CE} = 0.4 V	_	60		%
			I_F = 1 mA, V_{CE} = 0.4 V, GB Rank	30			
Collector-emitter saturation voltage	V _{CE(sat)}		I _F = 8 mA, I _C = 2.4 mA	_	_	0.3	V
			I _F = 1 mA, I _C = 0.2 mA	_	0.09		
			I_F = 1 mA, I_C = 0.2 mA, GB Rank	_	_	0.3	
OFF-state collector current	I _{C(off)}		V _{CE} = 48 V, V _F = 0.7 V	_	_	10	μА

Note 1: See Table 8.1 for current transfer ratio.

Table 8.1 Current Transfer Ratio (CTR) Rank (Note) (Unless otherwise specified, T_a = 25 °C)

Rank	Rank short code	Note	Test Condition	Current transfer ratio I _C /I _F Min	Current transfer ratio I _C /I _F Max	Marking of classification	Unit
Blank	_		I _F = 5 mA, V _{CE} = 5 V	50	600	Blank, YE, GR, GB, Y+,	%
			$I_F = 0.5 \text{ mA}, V_{CE} = 5 \text{ V}$			G, G+, BL, B	
Υ	_		$I_F = 5 \text{ mA}, V_{CE} = 5 \text{ V}$	50	150	YE	
			$I_F = 0.5 \text{ mA}, V_{CE} = 5 \text{ V}$				
GR	_		$I_F = 5 \text{ mA}, V_{CE} = 5 \text{ V}$	100	300	GR	
			$I_F = 0.5 \text{ mA}, V_{CE} = 5 \text{ V}$				
GB	_		$I_F = 5 \text{ mA}, V_{CE} = 5 \text{ V}$	100	600	GB, GR, BL	
			$I_F = 0.5 \text{ mA}, V_{CE} = 5 \text{ V}$				
BL	_		$I_F = 5 \text{ mA}, V_{CE} = 5 \text{ V}$	200	600	BL	
			$I_F = 0.5 \text{ mA}, V_{CE} = 5 \text{ V}$				
ΥH	_		$I_F = 0.5 \text{ mA}, V_{CE} = 5 \text{ V}$	75	150	Y+	
GRL	GL	(Note 1)	$I_F = 0.5 \text{ mA}, V_{CE} = 5 \text{ V}$	100	200	G	
GRH	GH	(Note 1)	$I_F = 0.5 \text{ mA}, V_{CE} = 5 \text{ V}$	150	300	G+	
BLL	В	(Note 1)	$I_F = 0.5 \text{ mA}, V_{CE} = 5 \text{ V}$	200	400	В	

Note: Specify both the part number and a rank in this format when ordering.

Example: TLP383(GB,E

For safety standard certification, however, specify the part number alone.

Example: TLP383(GB,E: TLP383

Note 1: A rank in the order name is sometimes omitted like above "Rank short code".



9. Isolation Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Total capacitance (input to output)	Cs	(Note 1)	V _S = 0 V, f = 1 MHz	_	0.8		pF
Isolation resistance	R _S	(Note 1)	V_S = 500 V, RH \leq 60 %	1012	1014		Ω
Isolation voltage	BVS	(Note 1)	AC, 60 s	5000	_		Vrms

Note 1: This device is considered as a two-terminal device: Pins 1 and 3 are shorted together, and pins 4 and 6 are shorted together.

10. Switching Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Rise time	t _r		V _{CC} = 10 V, I _C = 2 mA,	_	2	_	μS
Fall time	t _f		$R_L = 100 \Omega$		3	_	
Turn-on time	t _{on}			_	3	_	
Turn-off time	t _{off}			_	3	_	
Turn-on time	t _{on}		See Fig. 10.1.		0.95	_	
Storage time	t _s		$R_L = 1.9 \text{ k}\Omega, V_{CC} = 5 \text{ V},$ $I_F = 16 \text{ mA}$	_	14	_	
Turn-off time	t _{off}			_	28	_	
Turn-on time	t _{on}		See Fig. 10.1.	_	7.5	_	
Storage time	ts		$R_L = 4.7 \text{ k}\Omega, V_{CC} = 5 \text{ V},$	_	7	_	
Turn-off time	t _{off}		I _F = 1.6 mA		30	_	

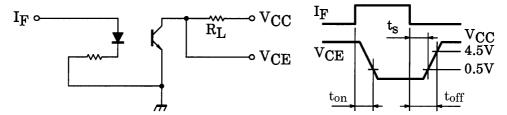


Fig. 10.1 Switching Time Test Circuit and Waveform



11. Characteristics Curves (Note)

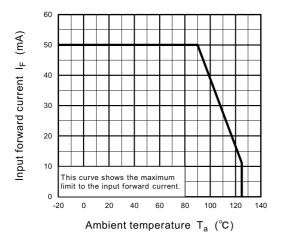


Fig. 11.1 IF - Ta

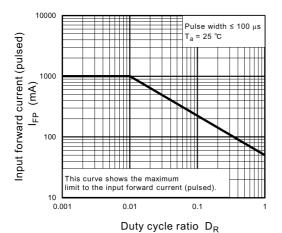


Fig. 11.3 IFP - DR

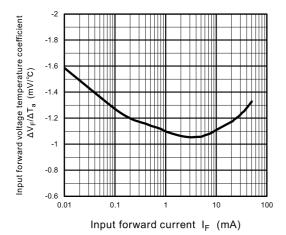


Fig. 11.5 $\Delta V_F/\Delta T_a - I_F$

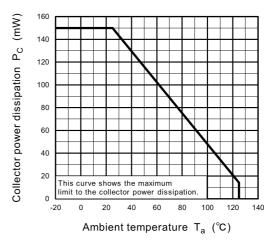


Fig. 11.2 P_C - T_a

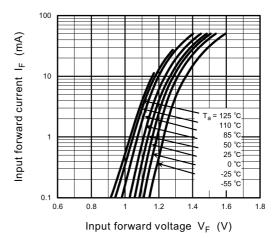
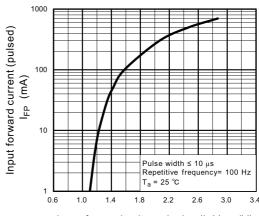


Fig. 11.4 I_F - V_F



Input forward voltage (pulsed) V_{FP} (V)

Fig. 11.6 IFP - VFP



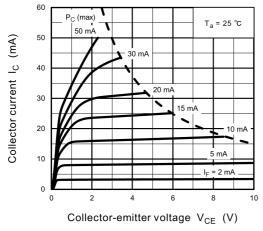


Fig. 11.7 I_C - V_{CE}

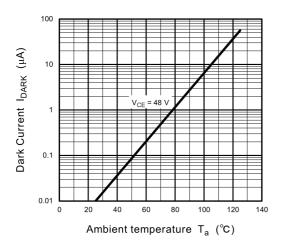


Fig. 11.9 IDARK - Ta

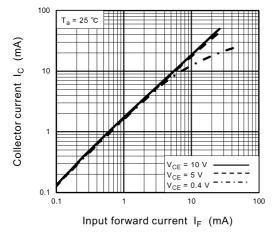


Fig. 11.11 Ic - IF

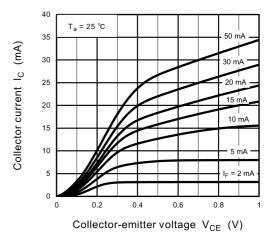


Fig. 11.8 I_C - V_{CE}

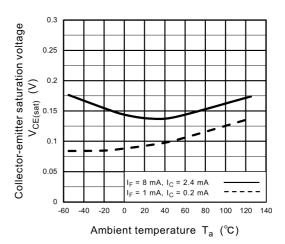


Fig. 11.10 V_{CE(sat)} - T_a

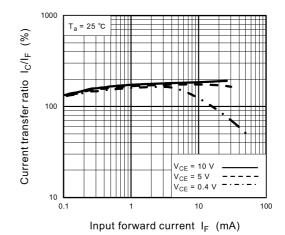


Fig. 11.12 I_C/I_F - I_F



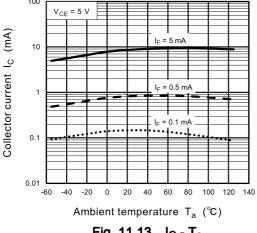


Fig. 11.13 I_C - T_a

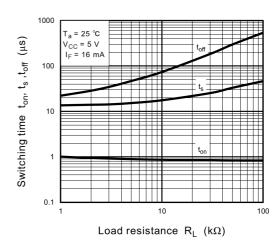


Fig. 11.14 Switching Time - RL

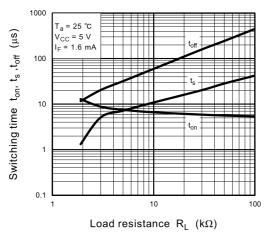


Fig. 11.15 Switching Time - RL

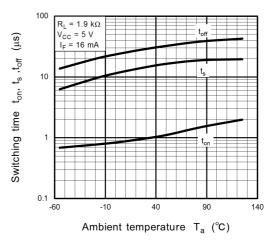


Fig. 11.16 Switching Time - Ta

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



12. Soldering and Storage

12.1. Precautions for Soldering

The soldering temperature should be controlled as closely as possible to the conditions shown below, irrespective of whether a soldering iron or a reflow soldering method is used.

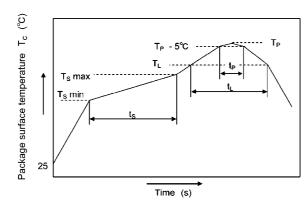
· When using soldering reflow.

The soldering temperature profile is based on the package surface temperature.

(See the figure shown below, which is based on the package surface temperature.)

Reflow soldering must be performed once or twice.

The mounting should be completed with the interval from the first to the last mountings being 2 weeks.



	Symbol	Min	Max	Unit
Preheat temperature	Ts	150	200	°C
Preheat time	ts	60	120	s
Ramp-up rate (T _L to T _P)			3	°C/s
Liquidus temperature	TL	2	17	°C
Time above T _L	t _L	60	150	s
Peak temperature	T _P		260	°C
Time during which T_c is between $(T_P - 5)$ and T_P	t _P		30	s
Ramp-down rate (T _P to T _L)			6	°C/s

Fig. 12.1.1 An Example of a Temperature Profile When Lead(Pb)-Free Solder Is Used

· When using soldering flow

Preheat the device at a temperature of 150 °C (package surface temperature) for 60 to 120 seconds. Mounting condition of 260 °C within 10 seconds is recommended.

Flow soldering must be performed once.

· When using soldering Iron

Complete soldering within 10 seconds for lead temperature not exceeding 260 °C or within 3 seconds not exceeding 350 °C

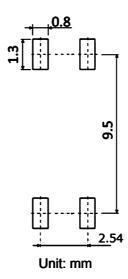
Heating by soldering iron must be done only once per lead.

12.2. Precautions for General Storage

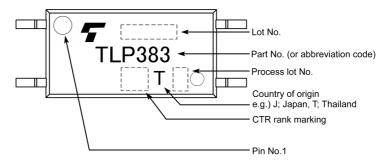
- Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Keep the storage location temperature and humidity within a range of 5 °C to 35 °C and 45 % to 75 %, respectively.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- · When restoring devices after removal from their packing, use anti-static containers.
- · Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.



13. Land Pattern Dimensions (for reference only)



14. Marking (Note)



Note: For the CTR rank mark, please refer to the marking of classification in table 8.1 CTR rank table.

Rev.7.0



15. EN 60747-5-5 Option (D4) Specification

Part number: TLP383 (Note 1)

The following part naming conventions are used for the devices that have been qualified according to option (D4) of EN 60747.

Example: TLP383(D4GR-TL,E

D4: EN 60747 option

GR: CTR rank

TL: Tape type (TPL)

E: [[G]]/RoHS COMPATIBLE (Note 2)

Note 1: Use TOSHIBA standard type number for safety standard application.

e.g., TLP383(D4GR-TL,E \rightarrow TLP383

Note 2: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.

RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

Description	Symbol	Rating	Unit
Application classification			
for rated mains voltage \leq 600 Vrms for rated mains voltage \leq 1000 Vrms		I-IV I-III	_
Climatic classification		55 / 125 / 21	_
Pollution degree		2	_
Maximum operating insulation voltage	VIORM	1230	Vpeak
Input to output test voltage, Method A V_{pr} = 1.6 × V_{IORM} , type and sample test t_p = 10 s, partial discharge < 5 pC	V _{pr}	1970	Vpeak
Input to output test voltage, Method B $V_{pr} = 1.875 \times V_{IORM}, \ 100 \ \% \ production \ test$ $t_p = 1 \ s, \ partial \ discharge < 5 \ pC$	V _{pr}	2310	Vpeak
Highest permissible overvoltage (transient overvoltage, t _{pr} = 60 s)	V _{TR}	8000	Vpeak
Safety limiting values (max. permissible ratings in case of fault, also refer to thermal derating curve) current (input current I _F , P _{SO} = 0) power (output or total power dissipation) temperature	I _{si} P _{so} T _s	250 400 150	mA mW °C
Insulation resistance V_{IO} = 500 V, T_a = 25 °C V_{IO} = 500 V, T_a = 100 °C V_{IO} = 500 V, T_a = T_s	R _{si}	≥ 10 ¹² ≥ 10 ¹¹ ≥ 10 ⁹	Ω

Fig. 15.1 EN 60747 Insulation Characteristics



Minimum creepage distance	Cr	8.0 mm
Minimum clearance	Cl	8.0 mm
Minimum insulation thickness	ti	0.4 mm
Comparative tracking index	СТІ	175

Fig. 15.2 Insulation Related Specifications (Note)

Note: This photocoupler is suitable for **safe electrical isolation** only within the safety limit data.

Maintenance of the safety data shall be ensured by means of protective circuits.



Fig. 15.3 Marking on packing

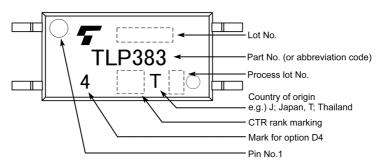
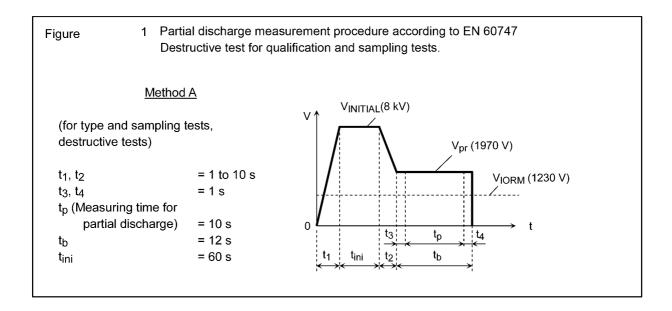
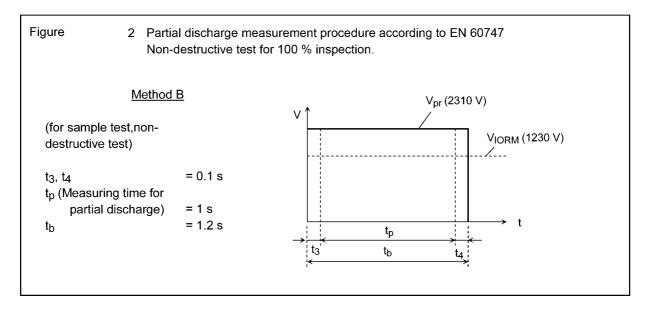


Fig. 15.4 Marking Example (Note)

 $Note: \quad \text{The above marking is applied to the photocouplers that have been qualified according to option (D4) of EN 60747.}$







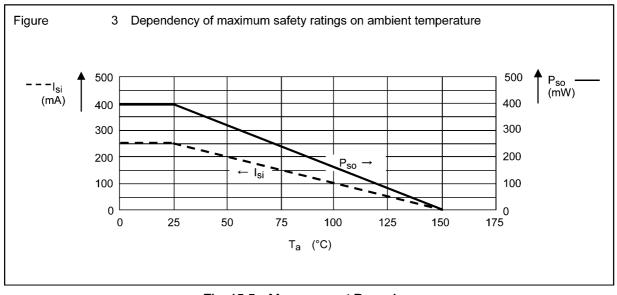
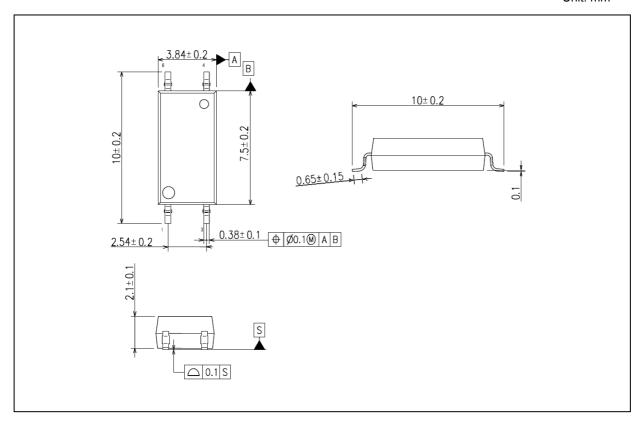


Fig. 15.5 Measurement Procedure



Package Dimensions

Unit: mm



Weight: 0.128 g (typ.)

	Package Name(s)
TOSHIBA: 11-4P1A	



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